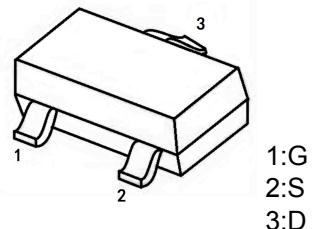


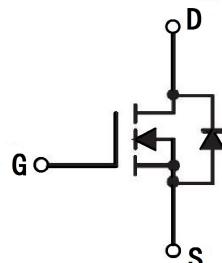
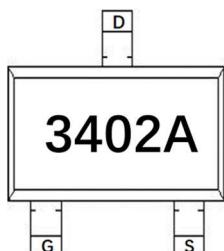
30V N-Channel Mosfet

FEATURES

- $R_{DS(ON)} \leq 42\text{m}\Omega$ (32m Ω Typ.) @ $V_{GS}=10\text{V}$
- $R_{DS(ON)} \leq 48\text{m}\Omega$ (36m Ω Typ.) @ $V_{GS}=4.5\text{V}$
- $R_{DS(ON)} \leq 70\text{m}\Omega$ (50m Ω Typ.) @ $V_{GS}=2.5\text{V}$

SOT-23**APPLICATIONS**

- PWM Applications
- Load Switch
- Power Management

N-CHANNEL MOSFET**MARKING:****Maximum ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current	$T_a = 25^\circ\text{C}$	A
		$T_a = 100^\circ\text{C}$	A
I_{DM}	Pulsed Drain Current note1	16	A
P_D	Power Dissipation	$T_a = 25^\circ\text{C}$	W
$R_{\theta JA}$	Thermal Resistance, Junction to Case	113.6	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS Ta=25 °C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5	0.9	1.4	V
R _{DS(on)} note2	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =4A	-	32	42	mΩ
		V _{GS} =4.5V, I _D =3A	-	36	48	
		V _{GS} =2.5V, I _D =2A	-	50	70	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1.0MHz	-	285	-	pF
C _{oss}	Output Capacitance		-	33	-	pF
C _{rss}	Reverse Transfer Capacitance		-	27	-	pF
Q _g	Total Gate Charge	V _{DS} =15V, I _D =4A, V _{GS} =4.5V	-	2.6	-	nC
Q _{gs}	Gate-Source Charge		-	0.6	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	0.9	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =15V, I _D =2A, R _{GEN} =3Ω, V _{GS} =4.5V	-	15	-	ns
t _r	Turn-on Rise Time		-	42	-	ns
t _{d(off)}	Turn-off Delay Time		-	16	-	ns
t _f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	4	A	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	16	A	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =4A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Characteristics

Figure 1: Output Characteristics

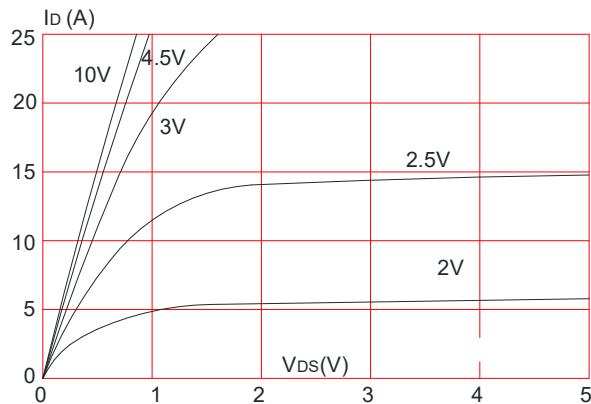


Figure 2: Typical Transfer Characteristics

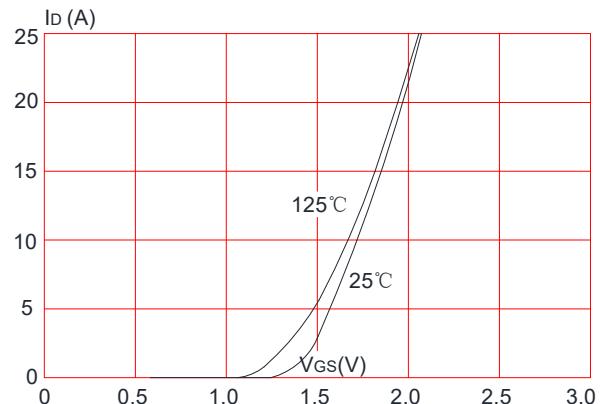


Figure 3: On-resistance vs. Drain Current

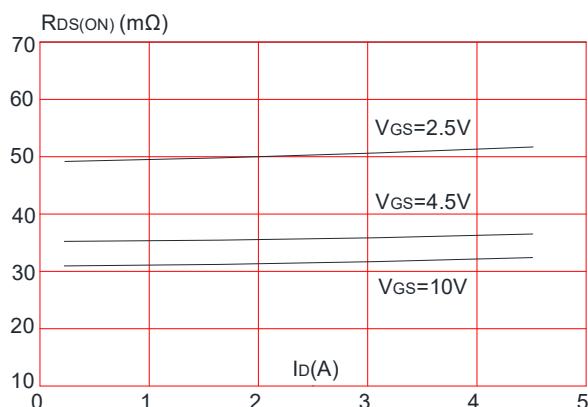


Figure 4: Body Diode Characteristics

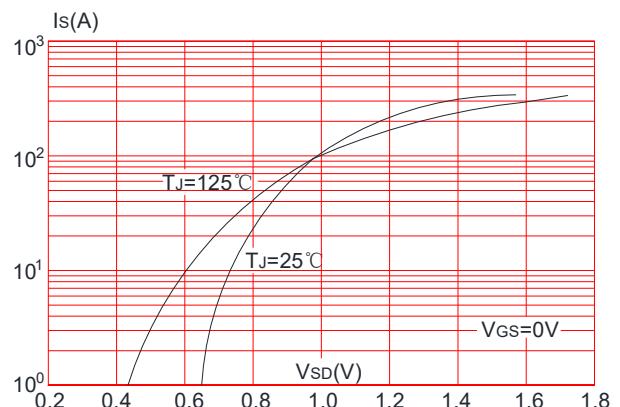


Figure 5: Gate Charge Characteristics

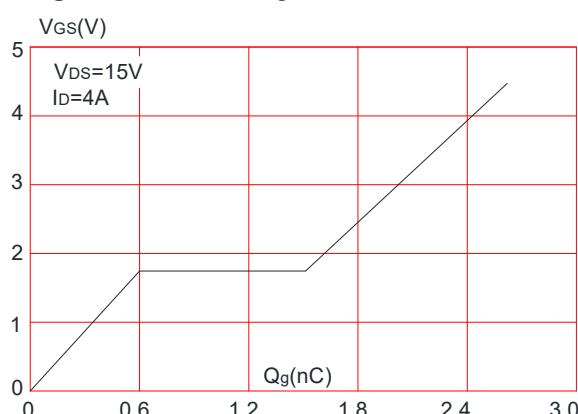
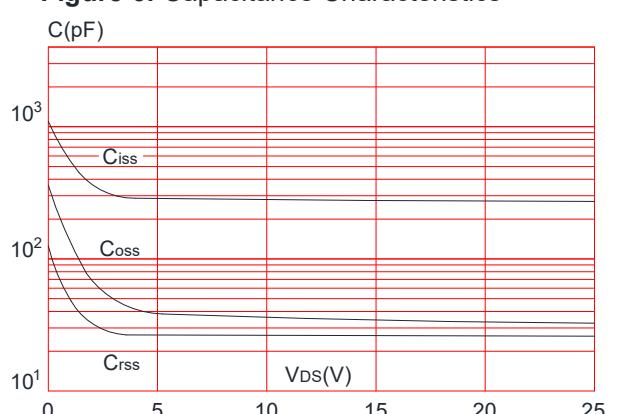


Figure 6: Capacitance Characteristics



Typical Characteristics (cont.)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

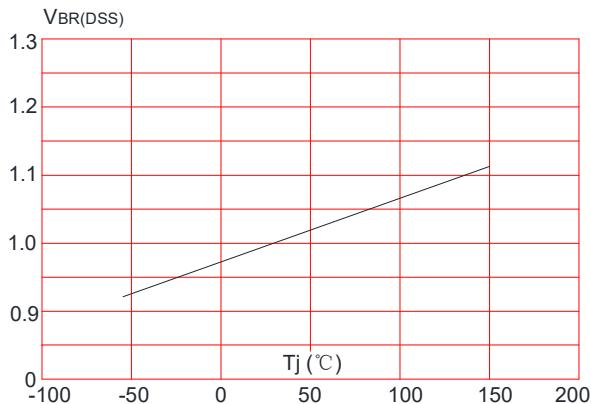


Figure 8: Normalized on Resistance vs. Junction Temperature

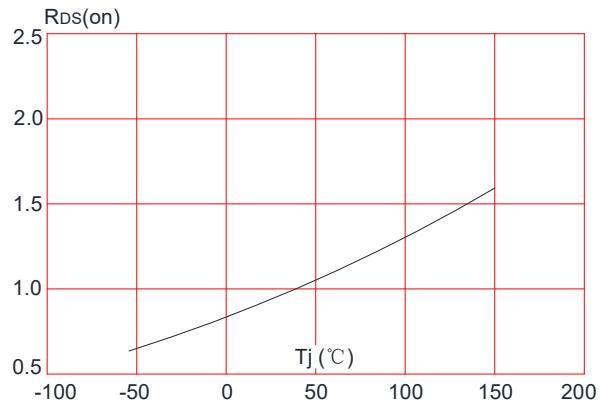


Figure 9: Maximum Safe Operating Area

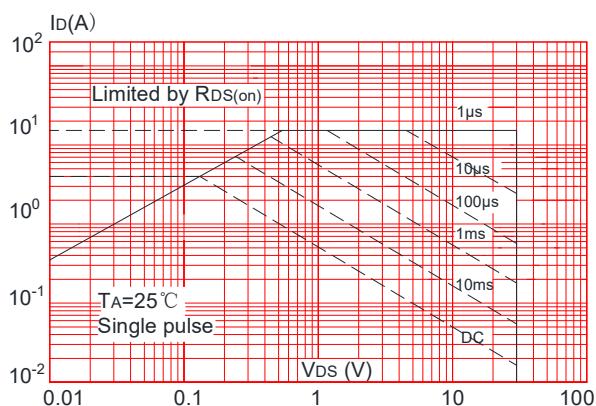


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

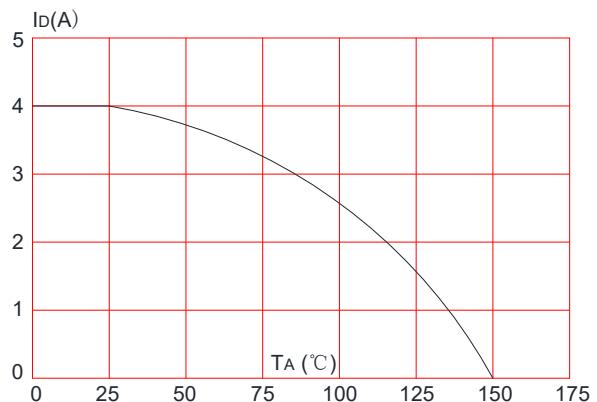
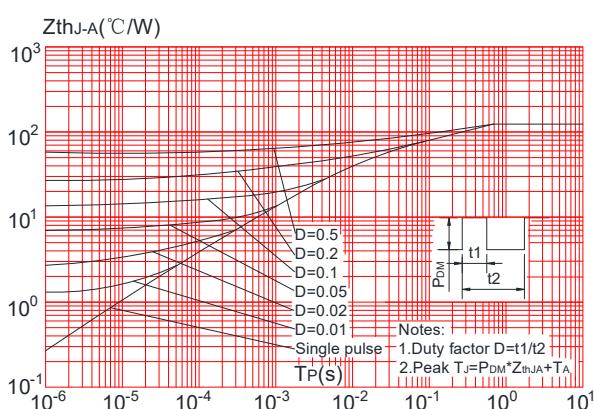
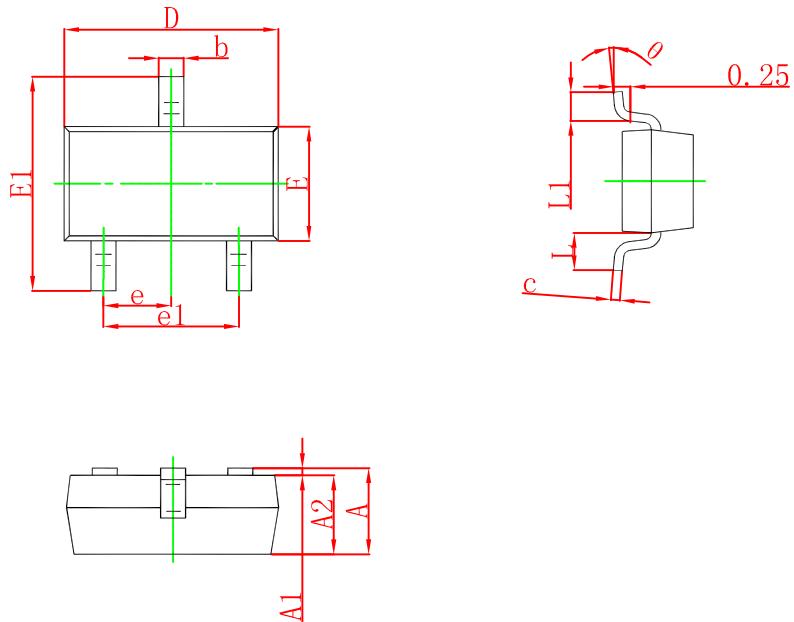


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



SOT-23 PACKAGE OUTLINE DRAWING



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°